



Product Change Notification

Change Notification #: 116777 - 00
Change Title: Intel® Dual Band Wireless-AC 3168 2230,
 SKUs: 3168.NGWG, 3168.NGWG.S
 PCN 116777-00, Label,
 Label Update
Date of Publication: February 20, 2019

Key Characteristics of the Change:
 Label

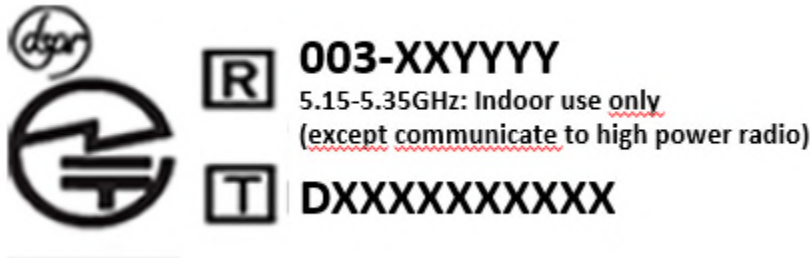
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	March 8, 2019
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Description of Change to the Customer:



The Intel® Wireless-AC 3168 2230 SKUs listed in the products affected table below will undergo the following changes:

1. Update to current Japan regulatory marking as below



2. The Intel Tracking revision will be changed on the following products

Product	Before	After
3168.NGWG	0F	0G

Product Code	Product Label (Before)	Product Label (After)
3168.NGWG	 <p>J21021-003</p> <p>Intel® Model: 3168NGW</p> <p>T PN: G86C0007K310 SPS : 852511-00 0F WFM: 000000XXXXXX BDM: 000000XXXXXX FCC ID: XXXXXXXXXX MM: XXXXXX TA: J20109-006 FRU P/N: 01AX706 EC: 274171</p> <p>MAIN 2 AUX 1</p> <p>8SXXXXXXXXXX T1SSYMDXXXX</p> <p>Made in China</p> <p>CE, FCC, RoHS</p> <p>MSIP-CRM-INT-3168NGW Anatel: 02218-16-02198 PTA APPROVED MODEL</p> <p>CMIT ID: 2016AJ0656 (M)</p> <p>R 003-160024 5.15-5.35 GHz Indoor use only D160013003</p> <p>CCAH16LP0440T9 IC :1000M-3168NG</p>	 <p>J21021-003</p> <p>Intel® Model: 3168NGW</p> <p>T PN: G86C0007K310 SPS : 852511-001 0G WFM: 000000XXXXXX BDM: 000000XXXXXX FCC ID: XXXXXXXXXX MM: XXXXXX TA: J20109-007 FRU P/N: 01AX706 EC: 274171</p> <p>MAIN 2 AUX 1</p> <p>8SXXXXXXXXXX T1SSYMDXXXX</p> <p>Made in China</p> <p>CE, FCC, RoHS</p> <p>MSIP-CRM-INT-3168NGW Anatel: 02218-16-02198 PTA APPROVED MODEL</p> <p>CMIT ID: 2016AJ0656 (M)</p> <p>R 003-160024 5.15-5.35GHz: Indoor use only (except continuous wave high power radio) D160013003</p> <p>CCAH16LP0440T9 IC :1000M-3168NG</p>

3168.NGWG IBL Label (Before)

<p>3168.NGWG</p> <p>VERSION #: J20109-006</p> <p>MADE IN CHINA WITH PARTIAL FOREIGN CONTENT CARTON #: VVXXXXXXXXXX</p>	<p>QTY: 100</p> <p>MM#: XXXXXX</p> <p>PACK DATE: DD MMM YY PACKED BY: XXXXXX</p> <p>BATCH #: CCVVYMDRSS</p>	<p>Intel® Dual Band Wireless-AC 3168 (Model: 3168NGW)</p> <p>PKG ID (3S) VVVVMMMDDD####PPPP100</p> <p>T PN: G86C0007K310</p> <p>D P/N: P P P P P P REV AX X HP P/N: 852510-001 R V: 0F</p> <p>PACKAGE WEIGHT: X.X LBS</p> <p>Vendor ID Loc ID Mfg Id VVVVV LLLLL MM MMM</p> <p>L P/N: SW10K97457 EC: 274171</p>	<p>CE, FCC, RoHS</p> <p>AT BE BG CH CY CZ DE DK EE EL ES FI FR HR HU IE IS IT LI LT LU LV MT NL PL PT RO SE SI SK TR UK</p> <p>Intel Corporation 2200 Mission College Blvd Santa Clara, CA 95054-1548 USA www.intel.com</p> <p>Complies with ICA Standards 0812161 E778A2</p> <p>CNC - CHINA NATIONAL FOUNDATION</p> <p>CNC ID: C-16378 CNC ID: C-16213</p> <p>MSIP-CRM-INT-3168NGW</p>
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3168.NGWG IBL Label (After)

<p>3168.NGWG</p> <p>VERSION #: J20109-007</p> <p>MADE IN CHINA WITH PARTIAL FOREIGN CONTENT CARTON #: VVXXXXXXXXXX</p>	<p>QTY: 100</p> <p>MM#: XXXXXX</p> <p>PACK DATE: DD MMM YY PACKED BY: XXXXXX</p> <p>BATCH #: CCVVYMDRSS</p>	<p>Intel® Dual Band Wireless-AC 3168 (Model: 3168NGW)</p> <p>PKG ID (3S) VVVVMMMDDD####PPPP100</p> <p>T PN: G86C0007K310</p> <p>D P/N: P P P P P P REV AX X HP P/N: 852510-001 R : 0G</p> <p>PACKAGE WEIGHT: X.X LBS</p> <p>Vendor ID Loc ID Mfg Id VVVVV LLLLL MM MMM</p> <p>L P/N: SW10K97457 EC: 274171</p>	<p>CE, FCC, RoHS</p> <p>AT BE BG CH CY CZ DE DK EE EL ES FI FR HR HU IE IS IT LI LT LU LV MT NL PL PT RO SE SI SK TR UK</p> <p>Intel Corporation 2200 Mission College Blvd Santa Clara, CA 95054-1548 USA www.intel.com</p> <p>Complies with ICA Standards 0812161 E778A2</p> <p>CNC - CHINA NATIONAL FOUNDATION</p> <p>CNC ID: C-16378 CNC ID: C-16213</p> <p>MSIP-CRM-INT-3168NGW</p>
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Product Code	Product Label (Before)	Product Label (After)
3168.NGWS.S	<p>J21021-003</p> <p>Intel® Model: 3168NGW</p> <p>T PN: G86C0007K410 SPS : XXXXXX-XXX XX WFM: OOOOOOXXXXXX BDM: OOOOOOXXXXXX FCC ID: XXXXXXXXX</p> <p>MM: XXXXXX TA: J20125-005 FRU P/N: 01AX707 EC: 274181</p> <p>8SSW10K97459 T1SSYMDXXXX</p> <p>Made in China</p> <p>CE, FCC, RoHS, and other regulatory logos.</p> <p>MSIP-CRM-INT-3168NGW Anatel: 02218-16-02198 PTA APPROVED MODEL CMIIT ID: 2016AJ0656 (M)</p> <p>003-160024 5.15-5.35 GHz: Indoor use only (except communicate to high power radio) D160013003</p> <p>CCA16LP0440T9 IC :1000M-3168NG</p>	<p>J21021-003</p> <p>Intel® Model: 3168NGW</p> <p>T PN: G86C0007K410 SPS : XXXXXX-XXX XX WFM: OOOOOOXXXXXX BDM: OOOOOOXXXXXX FCC ID: XXXXXXXXX</p> <p>MM: XXXXXX TA: J20125-006 FRU P/N: 01AX707 EC: 274181</p> <p>8SSW10K97459 T1SSYMDXXXX</p> <p>Made in China</p> <p>CE, FCC, RoHS, and other regulatory logos.</p> <p>MSIP-CRM-INT-3168NGW Anatel: 02218-16-02198 PTA APPROVED MODEL CMIIT ID: 2016AJ0656 (M)</p> <p>003-160024 5.15-5.35GHz: Indoor use only (except communicate to high power radio) D160013003</p> <p>CCA16LP0440T9 IC :1000M-3168NG</p>

3168.NGWS.S IBL Label (Before)

<p>3168.NGWS.S</p> <p>VERSION #: J20125-005</p> <p>MADE IN CHINA WITH PARTIAL FOREIGN CONTENT CARTON #: VVXXXXXXXX</p>	<p>QTY: 100</p> <p>MM#: XXXXXX</p> <p>PACK DATE: DD MMM YY PACKED BY: XXXXXX</p> <p>BATCH #: CCVVYMDRSS</p>	<p>Intel® Dual Band Wireless-AC 3168 (Model: 3168NGW)</p> <p>PKG ID (3S) VVVVMMMMDDO#####PPPPPP100</p> <p>T PN: G86C0007K410</p> <p>D P/N: P P P P P P REV AX X HP P/N: XXXXXX.XXX REV: XX</p> <p>PACKAGE WEIGHT: X.X LBS</p> <p>Vendor ID Loc Id Mfg Id L P/N: SW10K97459</p> <p>EC: 274181</p>	<p>Intel Corporation 2200 Mission College Blvd Santa Clara, CA 95054-1549 USA www.intel.com</p> <p>MSIP-CRM-INT-3168NGW</p>
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3168.NGWS.S IBL Label (After)

<p>3168.NGWS.S</p> <p>VERSION #: J20125-006</p> <p>MADE IN CHINA WITH PARTIAL FOREIGN CONTENT CARTON #: VVXXXXXXXX</p>	<p>QTY: 100</p> <p>MM#: XXXXXX</p> <p>PACK DATE: DD MMM YY PACKED BY: XXXXXX</p> <p>BATCH #: CCVVYMDRSS</p>	<p>Intel® Dual Band Wireless-AC 3168 (Model: 3168NGW)</p> <p>PKG ID (3S) VVVVMMMMDDO#####PPPPPP100</p> <p>T PN: G86C0007K410</p> <p>D P/N: P P P P P P REV AX X HP P/N: XXXXXX.XXX REV: XX</p> <p>PACKAGE WEIGHT: X.X LBS</p> <p>Vendor ID Loc Id Mfg Id L P/N: SW10K97459</p> <p>EC: 274181</p>	<p>Intel Corporation 2200 Mission College Blvd Santa Clara, CA 95054-1549 USA www.intel.com</p> <p>MSIP-CRM-INT-3168NGW</p>
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Customer Impact of Change and Recommended Action:

The label changes to the products do not affect functionality. Intel anticipates no impact to customers.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
3168.NGWG	944884	J20109-006	J20109-007
3168.NGWG.S	944885	J20125-005	J20125-006

PCN Revision History:

Date of Revision:
February 20, 2019

Revision Number:
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Reason:
Originally Published PCN



Product Change Notification

116777 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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